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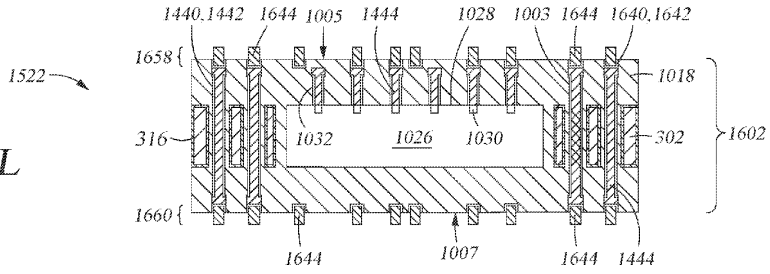


Fig. 16L

(57) Abstract: The present disclosure relates to thin-form-factor semiconductor device packages, and methods and systems for forming the same. Embodiments of the disclosure include methods and apparatus for forming semiconductor device packages that include frames that are coated with a layer of a coupling agent on which subsequently layers are formed. The utilization of the coupling agent between the frame and subsequently formed layers enhances the thermo-mechanical reliability of the package frames by mitigating the stress induced by any subsequently formed insulation layers and/or RDLs, and by providing improved coupling between such layers and the relatively smooth surfaces of the frames.

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